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## 7200CR SERIES

MANUAL EPOXY DIE BONDER

Continuing a ©radition of Duality

## 7200CR-Manual Epoxy Die Bonder



The fully programmable Microprocessor Controlled dispensing of epoxy ensures precise dot size. The EPOXY DISPENSE HEAD contains a 1cc reservoir for Epoxy. A variety of dispense needles are available to suit most applications. Dispense elevation is programmable. Following the dispense sequence; the machine automatically calls for the VACUUM PICKUP TOOL when the tool head assembly is lifted to a programmed elevation from the work. The Machine can be programmed for operator input to toggle between the EPOXY DISPENSE TOOL and the VACUUM PICKUP TOOL for pick and place operation.

The VACUUM PICKUP TOOL has a flat-faced Delrin tip with a vacuum through hole. A broad range of die sizes can be handled with a single tool. Die selected from practically any carrier media can be manipulated and rotated $\left(360^{\circ}\right)$ into position. Vacuum can be turned On or Off either by contact with the die surface or by control of the operator at any elevation.


## STANDARD SPECIFICATIONS:

CONTROL LOGIC: Motorola 68000 Microprocessor
MEMORY: 256KB RAM
DEVICE STORAGE: Single Device
DISPLAY: 40 Character, 4 Line LCD
Z-ENCODER RESOLUTION: 0.001"
TOOL Z RANGE: 0.625"
THROAT DEPTH: 5.25"
BOND FORCE RANGE: Adjustable, 5 - 75 grams ESD PROTECTION: Protection against Electrostatic Discharge

PICK-UP TOOL LENGTH: 0.625"
EPOXY DISPENSE NEEDLE LENGTH: 0.400"
EPOXY DISPENSE NEEDLE BORE: 0.006" - 0.073"
MICROMANIPULATOR: Counterbalanced, single lever X-Y-Z / 8:1 ratio
WORK PLATFORM: Fixed height. Adjustable height priced separately
MICROSCOPE: Selection available, (ESD types available)
ILLUMINATOR: Selection available, (ESD types available) WORK HOLDERS: Selection available, priced separately

